

## Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Drain-Source Voltage	V <sub>DSS</sub>	200	V
Gate-Source Voltage	V <sub>GSS</sub>	±20	V
Continuous Drain Current	I <sub>D</sub>	120	mA
Pulsed Drain Current	I <sub>DM</sub>	2	A

## Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P <sub>D</sub>	500	mW
Thermal Resistance, Junction to Ambient (Note 5)	R <sub>θJA</sub>	200	°C/W
Thermal Resistance, Junction to Leads (Note 6)	R <sub>θJL</sub>	71	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

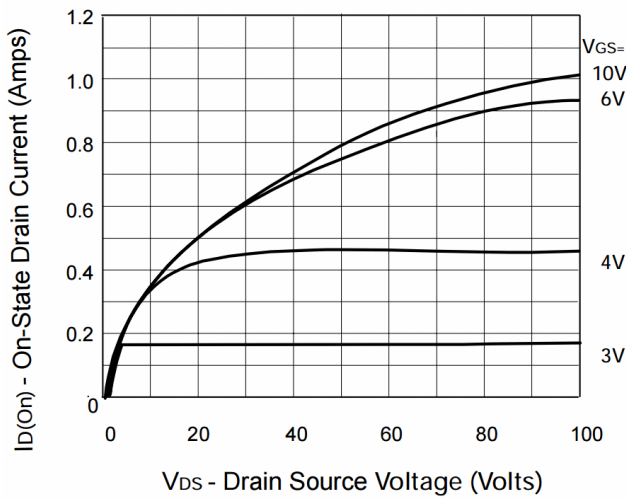
- Notes:
- For a through-hole device mounted on the minimum recommended pad layout with 12mm lead length from the bottom of package to the single-sided FR-4 PCB; device is measured under still air conditions whilst operating in a steady-state.
  - Thermal resistance from junction to solder-point at the seating plane (2.5mm from the bottom of package along the drain lead).

## Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

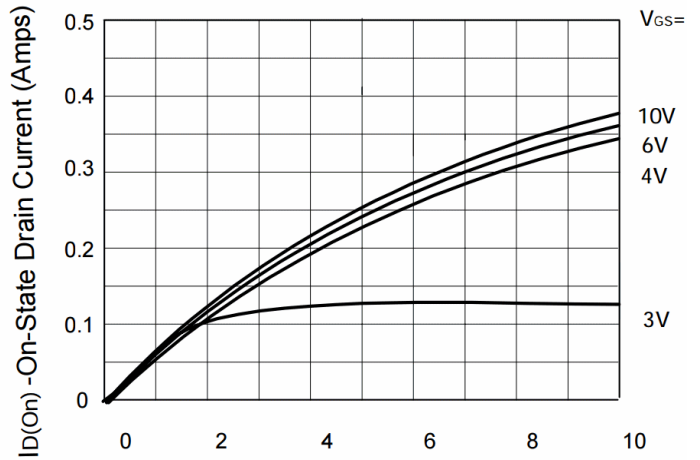
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	200	230	—	V	I <sub>D</sub> = 100μA, V <sub>GS</sub> = 0V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	—	—	30	nA	V <sub>DS</sub> = 130V, V <sub>GS</sub> = 0V
Drain Cut-Off Current	I <sub>DSX</sub>	—	—	1	μA	V <sub>DS</sub> = 70V, V <sub>GS</sub> = 0.2V
Gate-Source Leakage	I <sub>GSS</sub>	—	—	±10	nA	V <sub>GS</sub> = ±15V, V <sub>DS</sub> = 0V
<b>ON CHARACTERISTICS</b>						
Gate Threshold Voltage	V <sub>GS(TH)</sub>	1.0	—	3.0	V	I <sub>D</sub> = 1mA, V <sub>DS</sub> = V <sub>GS</sub>
Static Drain-Source On-Resistance (Note 7)	R <sub>DS(ON)</sub>	—	15	23	Ω	V <sub>GS</sub> = 2.6V, I <sub>D</sub> = 25mA
			—	30		V <sub>GS</sub> = 5V, I <sub>D</sub> = 100mA
Forward Transconductance (Notes 7 & 9)	g <sub>fs</sub>	100	—	—	mS	V <sub>DS</sub> = 25V, I <sub>D</sub> = 250mA
<b>DYNAMIC CHARACTERISTICS (Note 9)</b>						
Input Capacitance	C <sub>iss</sub>	—	—	85	pF	V <sub>DS</sub> = 25V, V <sub>GS</sub> = 0V f = 1.0MHz
Output Capacitance	C <sub>oss</sub>	—	—	20		
Reverse Transfer Capacitance	C <sub>rss</sub>	—	—	7		
Turn-On Delay Time (Note 8)	t <sub>D(ON)</sub>	—	—	7	ns	V <sub>DD</sub> = 25V, I <sub>D</sub> = 250mA
Turn-On Rise Time (Note 8)	t <sub>R</sub>	—	—	8		
Turn-Off Delay Time (Note 8)	t <sub>D(OFF)</sub>	—	—	16		
Turn-Off Fall Time (Note 8)	t <sub>F</sub>	—	—	8		

- Notes:
- Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%.
  - Switching characteristics are independent of operating junction temperature. Switching times are measured with 50Ω source impedance and <5ns rise time on a pulse generator.
  - For design aid only, not subject to production testing.

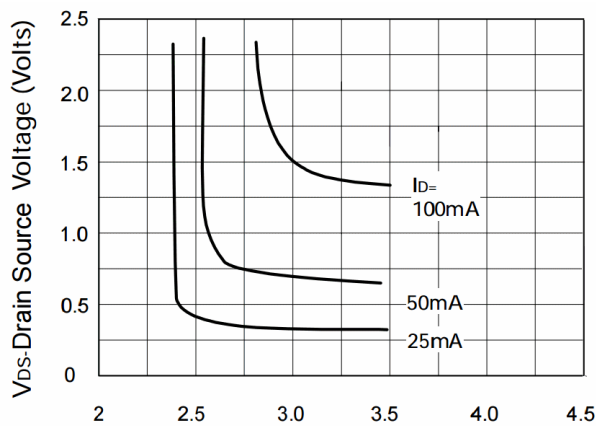
**Typical Electrical Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)



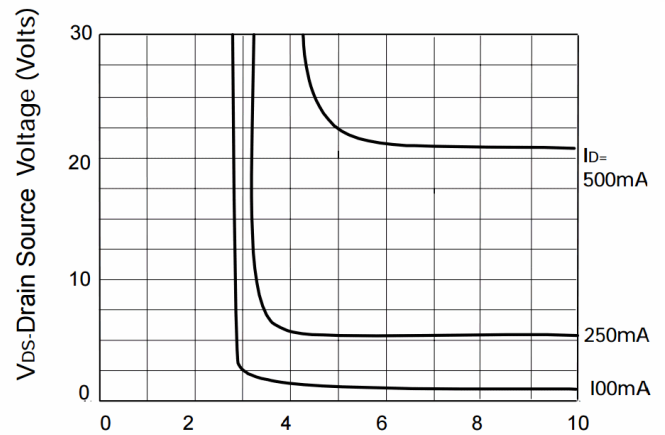
**Output Characteristics**



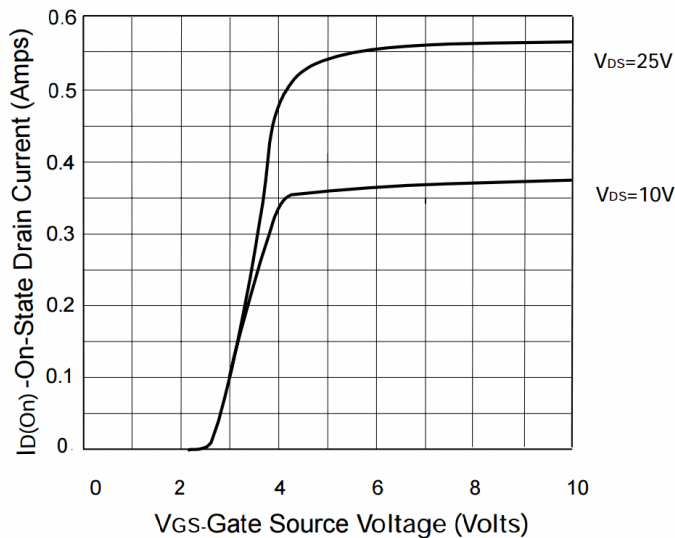
**Saturation Characteristics**



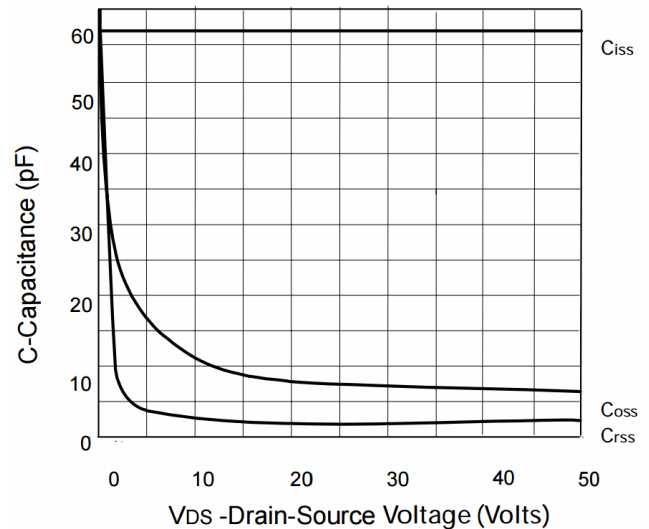
**Voltage Saturation Characteristics**



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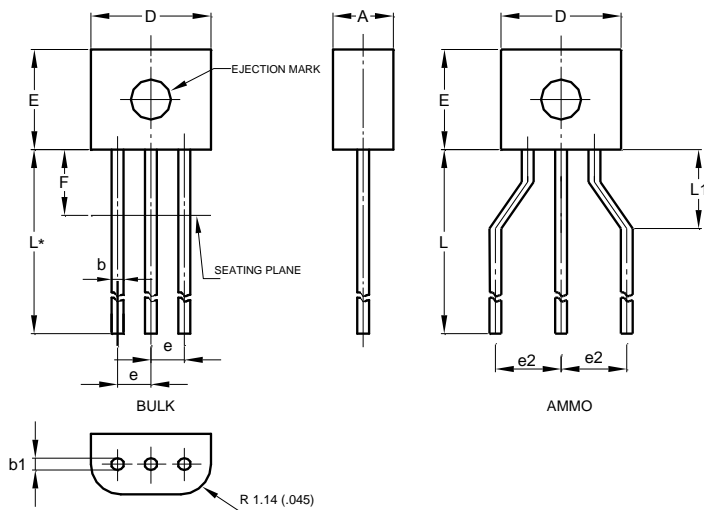
**Transfer characteristics**



**Capacitance v drain-source voltage**

## Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.



E-Line			
Dim	Min	Max	Typ
A	2.16	2.41	—
b	0.41	0.495	—
b1	0.41	0.495	—
D	4.37	4.77	—
E	3.61	4.01	—
e	—	—	1.27
e2	—	—	2.54
F	—	2.50	—
L	13.00	13.97	—
L1	2.50	3.50	—
All Dimensions in mm			

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